



#### **DESCRIPTION**

The 4435 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V.

#### **GENERAL FEATURES**

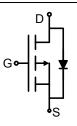
lacktriangle

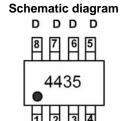
VDSS	RDS(ON) @-4.5V(Typ)	RDS(ON) @-10V(Typ)	lσ
-30V	20 mΩ	16 mΩ	-10A

- High Power and current handing capability
- RoHS Compliant
- Surface Mount Package

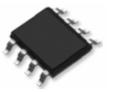
## **Application**

- Battery Switch
- Load switch
- Power management





**Marking and pin Assignment** 



SOP-8

## **Ordering Information**

	<u> </u>		
Part Number	Marking	Case	Packaging
4435	4435	SOP-8	2500pcs/Reel

## Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	-10	Α
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-50	Α
Maximum Power Dissipation	P <sub>D</sub>	3.1	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	℃

## **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	40	°C/W

## Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-30	-	-	V

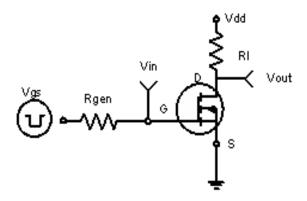


Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	•					
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1	-1.6	-2.5	V
Danie Course On Otata Basistana		V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	-	16	20	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	-	20	33	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-15V,I <sub>D</sub> =-10A	10	-	-	S
Dynamic Characteristics (Note4)	•					
Input Capacitance	C <sub>lss</sub>	\/ - 45\/\/ -0\/	-	1600	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, F=1.0MHz	-	350	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0IVIFIZ	-	300	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =-15V, ID=-1A,	-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{GEN}$ =6 $\Omega$	-	110	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	70	-	nS
Total Gate Charge	Qg	\/ - 15\/   - 100	-	30	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-15V, $I_{D}$ =-10A $V_{GS}$ =-10V	-	5.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS10V	-	8	-	nC
Drain-Source Diode Characteristics	•					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-5A	-	-	-1.2	

#### Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production

#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



**Figure 1:Switching Test Circuit** 

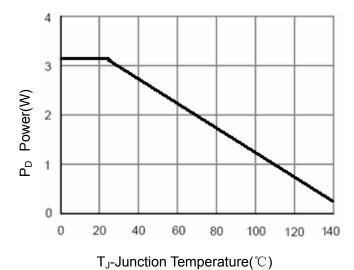
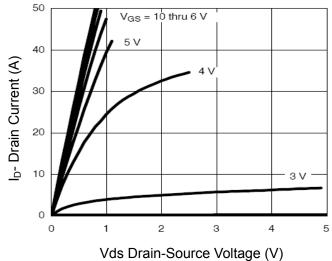


Figure 3 Power Dissipation



**Figure 5 Output CHARACTERISTICS** 

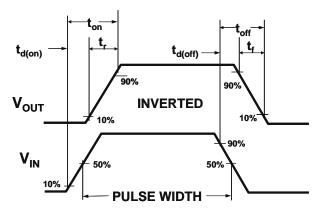
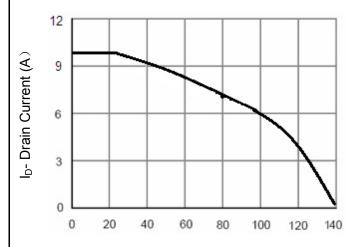
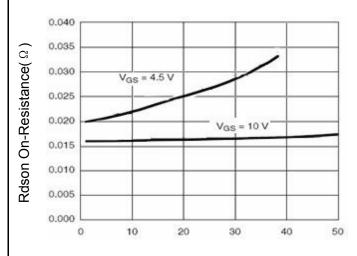


Figure 2:Switching Waveforms



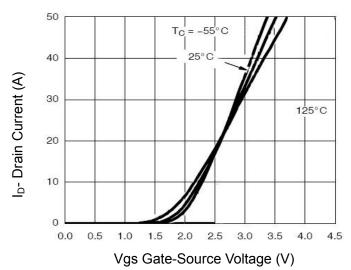
T<sub>J</sub>-Junction Temperature(°C)

Figure 4 Drain Current

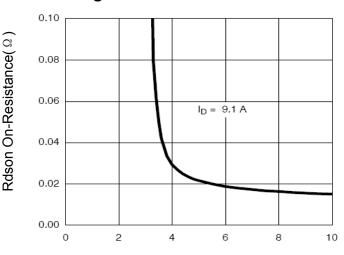


I<sub>D</sub>- Drain Current (A) Figure 6 Drain-Source On-Resistance

GOFORD 4435



**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

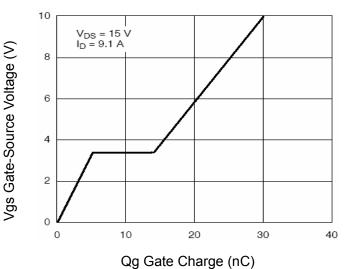


Figure 11 Gate Charge

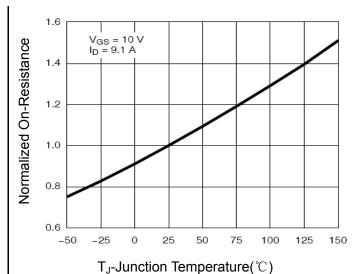
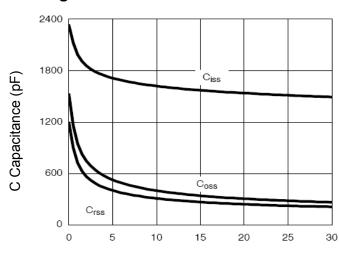


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

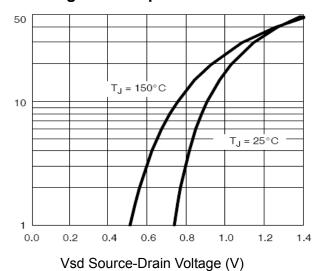
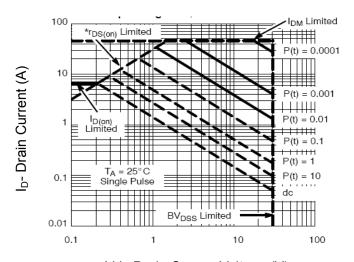


Figure 12 Source- Drain Diode Forward

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Is- Reverse Drain Current (A)



Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

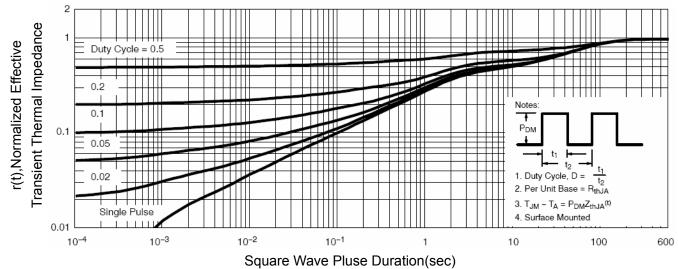
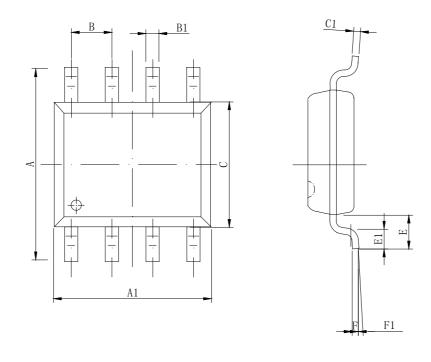
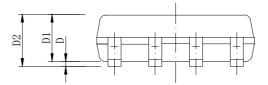


Figure 14 Normalized Maximum Transient Thermal Impedance

# **SOP-8 Package information**





DIM	MIN	NOM	MAX			
A	5. 800	6. 000	6. 200			
A1	4.800	4. 900	5. 000			
В		1. 270BSC				
B1	0.35 ^ 8x	0. 40 ^ 8x	0. 45 ^ 8x			
C	3. 780	3.880	3. 980			
C1	_	0. 203	0. 253			
D	0.050	0. 150	0. 250			
D1	1. 350	1. 450	1. 550			
D2	1. 500	1. 600	1. 700			
Е		1. 060 REF				
E1	0. 400	0.700	0. 100			
F		0. 250BSC				
F1	2°	4°	6°			

All Dimensions in mm